



SMD Auto X8G HT150C Flex, Ceramic, 330 pF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade, 1206, 1.5 mm



General Information		
Series	SMD Auto X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade	
Features	High Temperature, Ultra-Stable, Automotive Grade	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
Qualifications	AEC-Q200	
AEC-Q200	Yes	
Typical Component Weight	15 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
Packaging Specifications	

Packaging

Specifications		
Capacitance	330 pF	
Measurement Condition	1 MHz 1.0Vrms	
Tolerance	10%	
Voltage DC	250 VDC	
Dielectric Withstanding Voltage	625 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms	
Dissipation Factor	0.1% 1 MHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

Packaging Quantity	4000		
		Dissipation Factor	0.1% 1 MHz 1.0V
		Aging Rate	0% Loss/Deca Time is 1000 H

T&R, 180mm, Plastic Tape

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